

Title (en)

METHOD OF PRODUCING SEMICONDUCTOR SUBSTRATE PRODUCT AND ETCHING LIQUID

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES HALBLEITERSUBSTRATPRODUKTS UND EINER ÄTZFLÜSSIGKEIT

Title (fr)

PROCÉDÉ DE PRODUCTION D'UN PRODUIT CONSTITUÉ D'UN SUBSTRAT SEMI-CONDUCTEUR ET LIQUIDE DE GRAVURE

Publication

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Application

EP 13827735 A 20130724

Priority

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Abstract (en)

[origin: WO2014024737A1] A method of producing a semiconductor substrate product, having the steps of: providing a semiconductor substrate having two or more impurity-containing silicon layers and a silicon oxide layer, each of the impurity-containing silicon layers containing a different impurity from one another; applying an etching liquid onto the semiconductor substrate, the etching liquid comprising water, a hydrofluoric acid compound, and an anionic compound; and selectively etching the silicon oxide layer.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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